



LM2665 Switched Capacitor Voltage Converter

1 Features

- Input Voltage for Voltage Doubler: 2.5 V to 5.5 V
- Voltage Divider Splits Voltage: 1.8 V to 11 V
- Doubles or Splits Input Supply Voltage
- 12-Ω Typical Output Impedance
- 90% Typical Conversion Efficiency at 40 mA
- 1-μA Typical Shutdown Current

2 Applications

- Cellular Phones
- Pagers
- PDAs
- Operational Amplifier Power Suppliers
- Interface Power Suppliers
- Handheld Instruments
- Fire Detection and Notification
- Industrial Handheld Radios
- Blood Pressure Monitors

3 Description

The LM2665 CMOS charge-pump voltage converter operates as a voltage doubler for an input voltage in the range of 2.5 V to 5.5 V. Two low-cost capacitors and a diode (needed during start-up) are used in this circuit to provide up to 40 mA of output current. The LM2665 can also work as a voltage divider to split a voltage in the range of 1.8 V to 11 V in half.

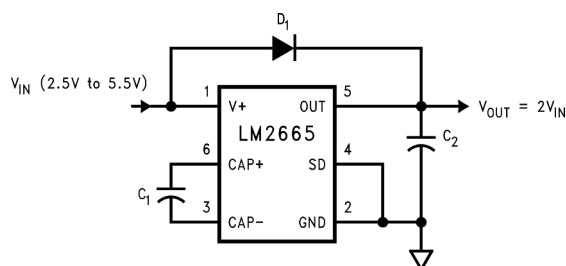
The LM2665 operates at 160-kHz oscillator frequency to reduce output resistance and voltage ripple. With an operating current of only 650 μA (operating efficiency greater than 90% with most loads) and 1-μA typical shutdown current, the LM2665 provides ideal performance for battery powered systems.

Device Information⁽¹⁾

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|-------------|------------|-------------------|
| LM2665 | SOT-23 (6) | 2.90 mm × 1.60 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Voltage Doubler



Splitting V_{IN} in Half

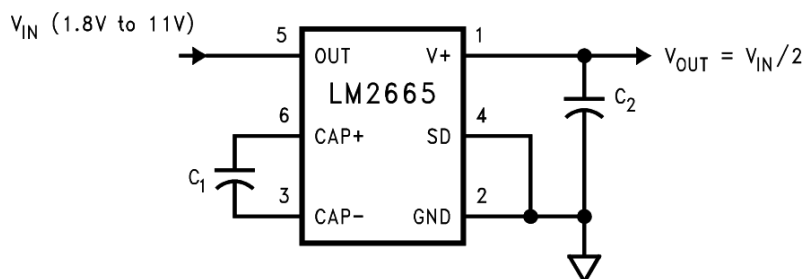


Table of Contents

| | | | |
|--|----------|--|-----------|
| 1 Features | 1 | 8.2 Functional Block Diagram | 8 |
| 2 Applications | 1 | 8.3 Feature Description | 8 |
| 3 Description | 1 | 8.4 Device Functional Modes | 8 |
| 4 Revision History | 2 | 9 Application and Implementation | 9 |
| 5 Pin Configuration and Functions | 3 | 9.1 Application Information | 9 |
| 6 Specifications | 4 | 9.2 Typical Applications | 9 |
| 6.1 Absolute Maximum Ratings | 4 | 10 Power Supply Recommendations | 12 |
| 6.2 ESD Ratings | 4 | 11 Layout | 13 |
| 6.3 Recommended Operating Conditions | 4 | 11.1 Layout Guidelines | 13 |
| 6.4 Thermal Information | 4 | 11.2 Layout Example | 13 |
| 6.5 Electrical Characteristics | 5 | 12 Device and Documentation Support | 14 |
| 6.6 Typical Characteristics | 5 | 12.1 Community Resources | 14 |
| 7 Parameter Measurement Information | 7 | 12.2 Trademarks | 14 |
| 7.1 Test Circuit | 7 | 12.3 Electrostatic Discharge Caution | 14 |
| 8 Detailed Description | 8 | 12.4 Glossary | 14 |
| 8.1 Overview | 8 | 13 Mechanical, Packaging, and Orderable Information | 14 |

4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision G (July 2015) to Revision H Page

- Added several new "Applications" to page 1 **1**

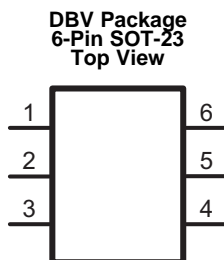
Changes from Revision F (May 2013) to Revision G Page

- Added *Pin Configuration and Functions* section, *ESD Rating* table, *Feature Description*, *Device Functional Modes*, *Application and Implementation*, *Power Supply Recommendations*, *Layout*, *Device and Documentation Support*, and *Mechanical, Packaging, and Orderable Information* sections **1**

Changes from Revision E (May 2013) to Revision F Page

- Changed layout of National Data Sheet to TI format **12**

5 Pin Configuration and Functions



Pin Functions

| PIN | | TYPE | DESCRIPTION | |
|-----|------|--------|---|-------------------------------------|
| NO. | NAME | | VOLTAGE DOUBLER | VOLTAGE SPLIT |
| 1 | V+ | Power | Power supply positive voltage input | Positive voltage output |
| 2 | GND | Ground | Power supply ground input | Same as doubler |
| 3 | CAP– | Power | Connect this pin to the negative terminal of the charge-pump capacitor. | Same as doubler |
| 4 | SD | Input | Shutdown control pin, tie this pin to ground in normal operation. | Same as doubler |
| 5 | OUT | Power | Positive voltage output | Power supply positive voltage input |
| 6 | CAP+ | Power | Connect this pin to the positive terminal of the charge-pump capacitor. | Same as doubler |

6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾⁽²⁾

| | MIN | MAX | UNIT |
|---|---------------|--------------|------|
| V+ to GND voltage | | 5.8 | V |
| OUT to GND voltage | | 11.6 | V |
| OUT to V+ voltage | | 5.8 | V |
| SD | (GND – 0.3 V) | (V+ + 0.3 V) | |
| V+ and OUT continuous output current | | 50 | mA |
| Output short-circuit duration to GND ⁽³⁾ | | 1 | sec |
| Continuous power dissipation (T _A = 25°C) ⁽⁴⁾ | | 600 | mW |
| T _{J-MAX} ⁽⁴⁾ | | 150 | °C |
| Lead temperature (soldering, 10 sec.) | | 300 | °C |
| Storage temperature, T _{stg} | –65 | 150 | °C |

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (3) OUT may be shorted to GND for one second without damage. However, shorting OUT to V+ may damage the device and must be avoided. Also, for temperatures above 85°C, OUT must not be shorted to GND or V+, or device may be damaged.
- (4) The maximum allowable power dissipation is calculated by using $P_{D-MAX} = (T_{J-MAX} - T_A)/R_{\theta JA}$, where T_{J-MAX} is the maximum junction temperature, T_A is the ambient temperature, and R_{θJA} is the junction-to-ambient thermal resistance of the specified package.

6.2 ESD Ratings

| | VALUE | UNIT |
|--|-------|------|
| V _(ESD) Electrostatic discharge Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾ | ±2000 | V |

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

| | MIN | NOM | MAX | UNIT |
|--------------------------------|-----|-----|-----|------|
| Operating junction temperature | –40 | | 85 | °C |

6.4 Thermal Information

| THERMAL METRIC ⁽¹⁾ | LM2665 | UNIT |
|---|--------------|------|
| | DBV (SOT-23) | |
| | 6 PINS | |
| R _{θJA} Junction-to-ambient thermal resistance | 210 | °C/W |

- (1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

MIN and MAX limits apply over the full operating temperature range. Unless otherwise specified: $T_J = 25^\circ\text{C}$, $V_+ = 5\text{ V}$, $C_1 = C_2 = 3.3\text{ }\mu\text{F}$.⁽¹⁾

| PARAMETER | TEST CONDITIONS | MIN ⁽²⁾ | TYP ⁽³⁾ | MAX ⁽²⁾ | UNIT |
|------------|--|---|--------------------|--------------------|---------------|
| V_+ | Supply voltage | 2.5 | | 5.5 | V |
| I_Q | Supply current | No load | | 650 | μA |
| I_{SD} | Shutdown supply current | | | 1 | μA |
| V_{SD} | Shutdown pin input voltage | Normal operation | | 2 ⁽⁴⁾ | V |
| | | Shutdown mode | | 0.8 ⁽⁵⁾ | |
| I_L | Output current | 40 | | | mA |
| R_{SW} | Sum of the $R_{ds(on)}$ of the four internal MOSFET switches | $I_L = 40\text{ mA}$ | | 3.5 | Ω |
| R_{OUT} | Output resistance ⁽⁶⁾ | $I_L = 40\text{ mA}$ | | 12 | Ω |
| f_{OSC} | Oscillator frequency | See ⁽⁷⁾ | | 80 | kHz |
| f_{SW} | Switching frequency | See ⁽⁷⁾ | | 40 | kHz |
| P_{EFF} | Power efficiency | R_L (1 k Ω) between GND and OUT | | 90% | |
| | | $I_L = 40\text{ mA}$ to GND | | 94% | |
| V_{OEFF} | Voltage conversion efficiency | No load | | 99% | 99.96% |

- (1) In the test circuit, capacitors C_1 and C_2 are 3.3- μF , 0.3- Ω maximum ESR capacitors. Capacitors with higher ESR increase output resistance, reduce output voltage and efficiency.
- (2) Min. and Max. limits are ensured by design, test, or statistical analysis.
- (3) Typical numbers are not ensured but represent the most likely norm.
- (4) The minimum input high for the SD pin equals 40% of V_+ .
- (5) The maximum input low for the SD pin equals 20% of V_+ .
- (6) Specified output resistance includes internal switch resistance and capacitor ESR. See the details in [Application and Implementation](#) for simple negative voltage converter.
- (7) The output switches operate at one half of the oscillator frequency, $f_{OSC} = 2f_{SW}$.

6.6 Typical Characteristics

(Circuit of [Figure 9](#), $V_+ = 5\text{ V}$ unless otherwise specified)

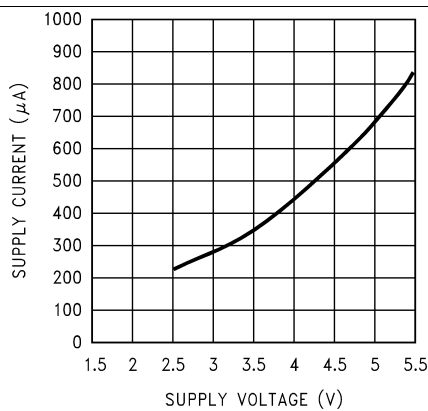


Figure 1. Supply Current vs Supply Voltage

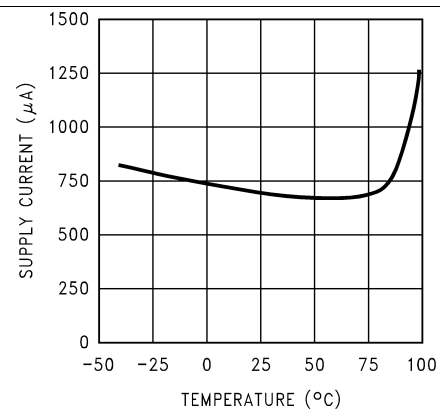


Figure 2. Supply Current vs Temperature

Typical Characteristics (continued)

(Circuit of [Figure 9](#), $V_+ = 5\text{ V}$ unless otherwise specified)

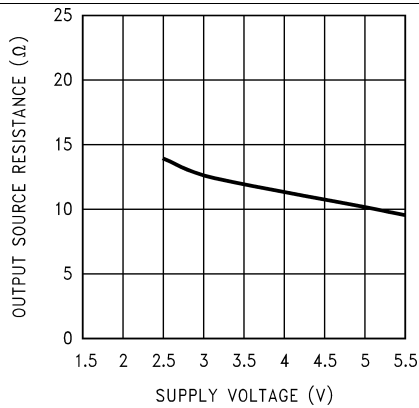


Figure 3. Output Source Resistance vs Supply Voltage

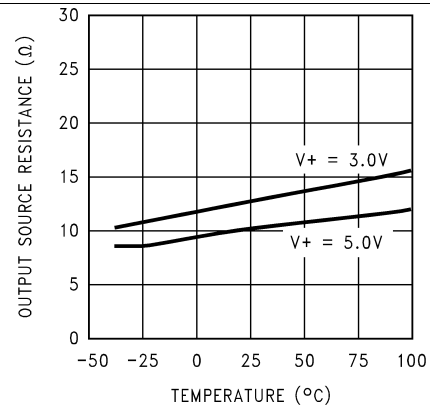


Figure 4. Output Source Resistance vs Temperature

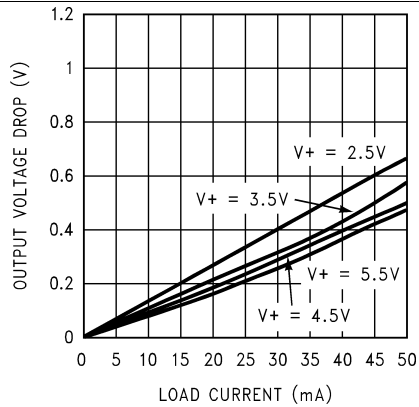


Figure 5. Output Voltage Drop vs Load Current

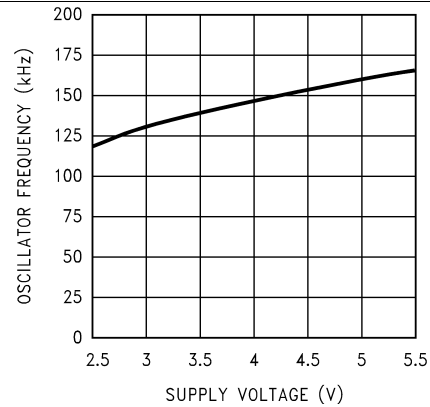


Figure 6. Oscillator Frequency vs Supply Voltage

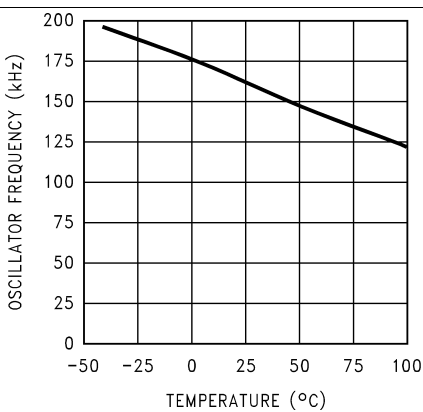


Figure 7. Oscillator Frequency vs Temperature

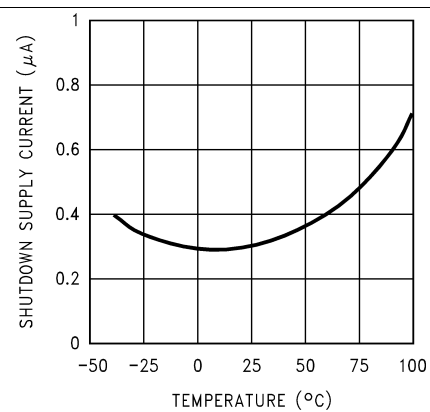
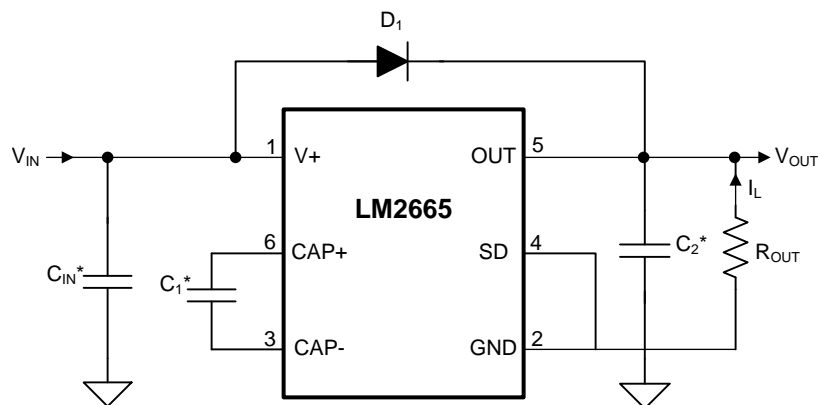


Figure 8. Shutdown Supply Current vs Temperature

7 Parameter Measurement Information

7.1 Test Circuit



* C_{IN} , C_1 and C_2 are 3.3 μ F OS-CON capacitors.

Figure 9. LM2665 Test Circuit

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers must validate and test their design implementation to confirm system functionality.

9.1 Application Information

The LM2665 provides a simple and efficient means of creating an output voltage level equal to twice that of the input voltage. Without the need of an inductor, the application solution size can be reduced versus the magnetic DC-DC converter solution.

9.2 Typical Applications

9.2.1 Voltage Doubler

The main application of the LM2665 is to double the input voltage. The range of the input supply voltage is 2.5 V to 5.5 V.

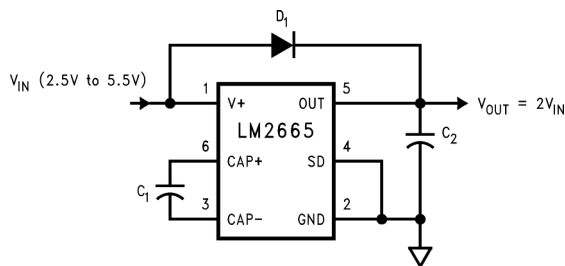


Figure 11. Voltage Doubler

9.2.1.1 Design Requirements

Example requirements for LM2665 device applications:

| DESIGN PARAMETER | EXAMPLE VALUE |
|---------------------------|----------------|
| Input voltage range | 2.5 V to 5.5 V |
| Output current | 0 mA to 40 mA |
| Boost switching frequency | 80 kHz |

9.2.1.2 Detailed Design Requirements

9.2.1.2.1 Positive Voltage Doubler

The output characteristics of this circuit can be approximated by an ideal voltage source in series with a resistance. The voltage source equals $2V_+$. The output resistance R_{OUT} is a function of the ON resistance of the internal MOSFET switches, the oscillator frequency, the capacitance and equivalent series resistance (ESR) of C_1 and C_2 . Since the switching current charging and discharging C_1 is approximately twice as the output current, the effect of the ESR of the pumping capacitor C_1 will be multiplied by four in the output resistance. The output capacitor C_2 is charging and discharging at a current approximately equal to the output current, therefore, its ESR only counts when in the output resistance. A good approximation of R_{OUT} is:

$$R_{OUT} \cong 2R_{SW} + \frac{2}{f_{OSC} \times C_1} + 4ESR_{C1} + ESR_{C2}$$

where

- R_{SW} is the sum of the ON resistance of the internal MOSFET switches shown in [Figure 10](#). (1)

The peak-to-peak output voltage ripple is determined by the oscillator frequency, the capacitance and ESR of the output capacitor C_2 :

$$V_{RIPPLE} = \frac{I_L}{f_{OSC} \times C_2} + 2 \times I_L \times ESR_{C2} \quad (2)$$

High capacitance, low-ESR capacitors can reduce both the output resistance and the voltage ripple.

The Schottky diode D_1 is only needed for start-up. The internal oscillator circuit uses the OUT pin and the GND pin. Voltage across OUT and GND must be larger than 1.8 V to insure the operation of the oscillator. During start-up, D_1 is used to charge up the voltage at the OUT pin to start the oscillator; also, it protects the device from turning-on its own parasitic diode and potentially latching-up. Therefore, the Schottky diode D_1 must have enough current carrying capability to charge the output capacitor at start-up, as well as a low forward voltage to prevent the internal parasitic diode from turning-on. A Schottky diode like 1N5817 can be used for most applications. If the input voltage ramp is less than 10 V/ms, a smaller Schottky diode like MBR0520LT1 can be used to reduce the circuit size.

9.2.1.2.2 Capacitor Selection

As discussed in [Positive Voltage Doubler](#), the output resistance and ripple voltage are dependent on the capacitance and ESR values of the external capacitors. The output voltage drop is the load current times the output resistance, and the power efficiency is:

$$\eta = \frac{P_{OUT}}{P_{IN}} = \frac{I_L^2 R_L}{I_L^2 R_L + I_L^2 R_{OUT} + I_Q(V_+)}$$

where

- $I_Q(V_+)$ is the quiescent power loss of the IC device; and
- $I_L^2 R_{out}$ is the conversion loss associated with the switch on-resistance, the two external capacitors and their ESRs. (3)

The selection of capacitors is based on the specifications of the dropout voltage (which equals $I_{OUT} R_{OUT}$), the output voltage ripple, and the converter efficiency. Low ESR capacitors are recommended to maximize efficiency, reduce the output voltage drop and voltage ripple.

9.2.1.2.3 Paralleling Devices

Any number of LM2665 devices can be paralleled to reduce the output resistance. Each device must have its own pumping capacitor C_1 , while only one output capacitor C_{OUT} is needed as shown in [Figure 12](#). The composite output resistance is:

$$R_{OUT} = \frac{R_{OUT \text{ of each LM2665}}}{\text{Number of Devices}} \quad (4)$$

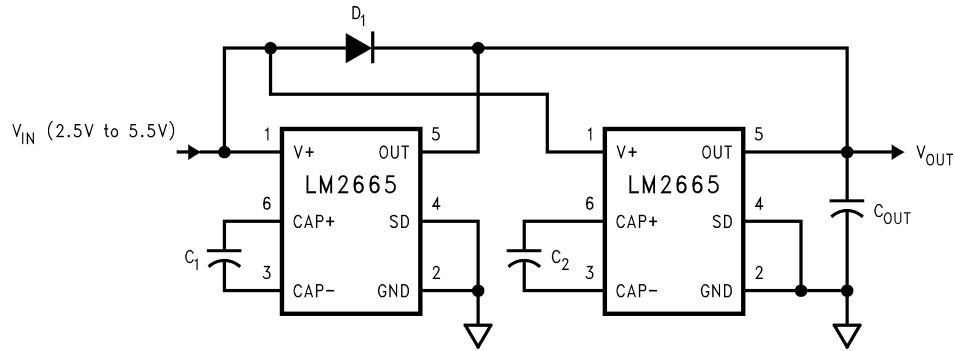


Figure 12. Lowering Output Resistance By Paralleling Devices

9.2.1.2.4 Cascading Devices

Cascading the LM2665 devices is an easy way to produce a greater voltage (a two-stage cascade circuit is shown in Figure 13).

The effective output resistance is equal to the weighted sum of each individual device:

$$R_{OUT} = 1.5 R_{OUT_1} + R_{OUT_2} \quad (5)$$

Note that the increasing of the number of cascading stages is practically limited since it significantly reduces the efficiency, increases the output resistance and output voltage ripple.

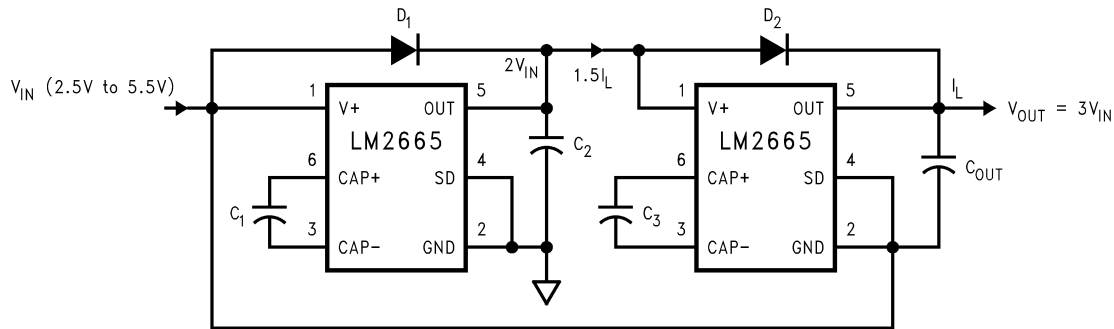


Figure 13. Increasing Output Voltage By Cascading Devices

9.2.1.2.5 Regulating V_OUT

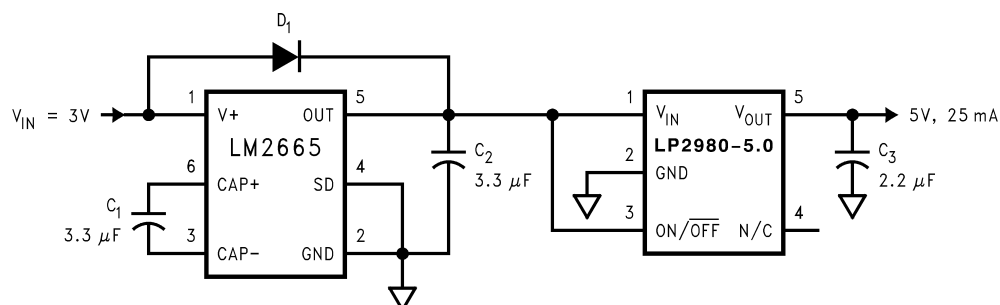
It is possible to regulate the output of the LM2665 by use of a low dropout regulator (such as LP2980-5.0). The whole converter is depicted in Figure 14.

A different output voltage is possible by use of LP2980-3.3, LP2980-3.0, or LP2980-ADJ.

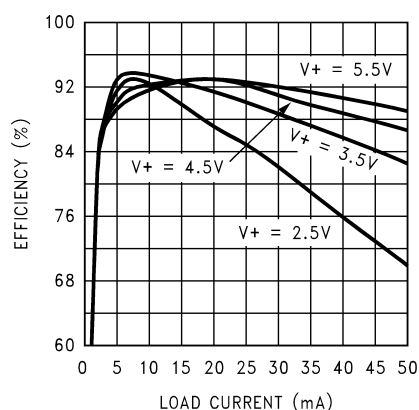
Note that the following conditions must be satisfied simultaneously for worst-case design:

$$2V_{IN_MIN} > V_{OUT_MIN} + V_{DROP_MAX} (LP2980) + I_{OUT_MAX} \times R_{OUT_MAX} (LM2665) \quad (6)$$

$$2V_{IN_MAX} < V_{OUT_MAX} + V_{DROP_MIN} (LP2980) + I_{OUT_MIN} \times R_{OUT_MIN} (LM2665) \quad (7)$$

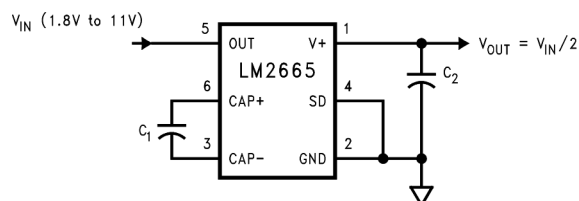

Figure 14. Generate a Regulated 5-V from 3-V Input Voltage

9.2.1.3 Application Curve


Figure 15. Efficiency vs Load Current

9.2.2 Splitting V+ In Half

Another interesting application shown in [Splitting \$V_{in}\$ in Half](#) is using the LM2665 as a precision voltage divider. This circuit can be derived from the voltage doubler by switching the input and output connections. In the voltage divider, the input voltage applies across the OUT pin and the GND pin (which are the power rails for the internal oscillator), therefore no start-up diode is needed. Also, since the off-voltage across each switch equals $V_{IN}/2$, the input voltage can be raised to 11 V.


Figure 16. Application Circuit for Splitting Voltage

10 Power Supply Recommendations

The LM2665 is designed to operate from as an inverter over an input voltage supply range between 2.5 V and 5.5 V when the LV pin is grounded. This input supply must be well regulated and capable to supply the required input current. If the input supply is located far from the device, additional bulk capacitance may be required in addition to the ceramic bypass capacitors.

11 Layout

11.1 Layout Guidelines

The high switching frequency and large switching currents of the LM2665 make the choice of layout important. Use the following steps as a reference to ensure the device is stable and maintains proper LED current regulation across its intended operating voltage and current range.

- Place C_{IN} on the top layer (same layer as the LM2665) and as close to the device as possible. Connecting the input capacitor through short, wide traces to both the V+ and GND pins reduces the inductive voltage spikes that occur during switching which can corrupt the V+ line.
- Place C_{OUT} on the top layer (same layer as the LM2665) and as close as possible to the OUT and GND pin. The returns for both C_{IN} and C_{OUT} must come together at one point, as close to the GND pin as possible. Connecting C_{OUT} through short, wide traces reduce the series inductance on the OUT and GND pins that can corrupt the V_{OUT} and GND lines and cause excessive noise in the device and surrounding circuitry.
- Place C1 on the top layer (same layer as the LM2665 device) and as close to the device as possible. Connect the flying capacitor through short, wide traces to both the CAP+ and CAP– pins.

11.2 Layout Example

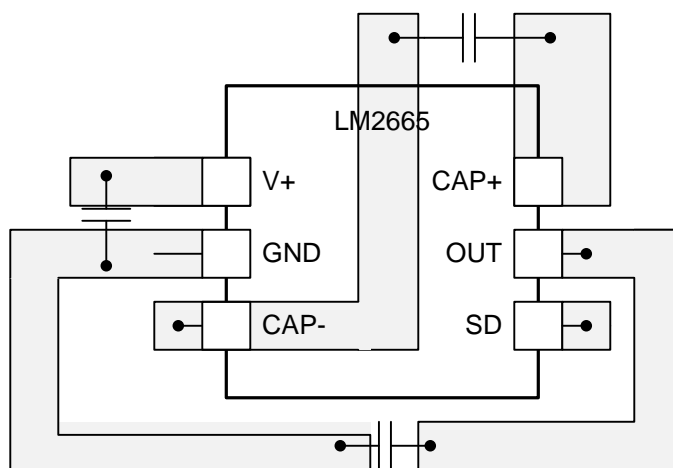


Figure 17. Typical Layout for LM2665

12 Device and Documentation Support

12.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.2 Trademarks

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

12.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| LM2665M6 | NRND | SOT-23 | DBV | 6 | 1000 | TBD | Call TI | Call TI | -40 to 85 | S04A | |
| LM2665M6/NOPB | ACTIVE | SOT-23 | DBV | 6 | 1000 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | S04A | Samples |
| LM2665M6X | NRND | SOT-23 | DBV | 6 | 3000 | TBD | Call TI | Call TI | -40 to 85 | S04A | |
| LM2665M6X/NOPB | ACTIVE | SOT-23 | DBV | 6 | 3000 | Green (RoHS & no Sb/Br) | CU SN | Level-1-260C-UNLIM | -40 to 85 | S04A | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| LM2665M6 | SOT-23 | DBV | 6 | 1000 | 178.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| LM2665M6/NOPB | SOT-23 | DBV | 6 | 1000 | 178.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| LM2665M6X | SOT-23 | DBV | 6 | 3000 | 178.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |
| LM2665M6X/NOPB | SOT-23 | DBV | 6 | 3000 | 178.0 | 8.4 | 3.2 | 3.2 | 1.4 | 4.0 | 8.0 | Q3 |

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

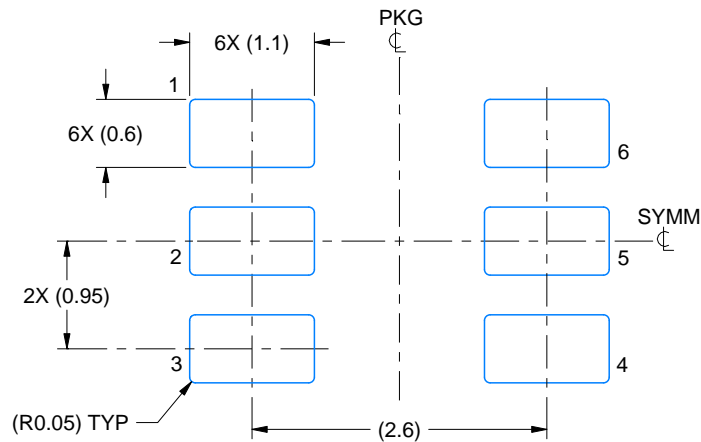
| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| LM2665M6 | SOT-23 | DBV | 6 | 1000 | 210.0 | 185.0 | 35.0 |
| LM2665M6/NOPB | SOT-23 | DBV | 6 | 1000 | 210.0 | 185.0 | 35.0 |
| LM2665M6X | SOT-23 | DBV | 6 | 3000 | 210.0 | 185.0 | 35.0 |
| LM2665M6X/NOPB | SOT-23 | DBV | 6 | 3000 | 210.0 | 185.0 | 35.0 |

EXAMPLE BOARD LAYOUT

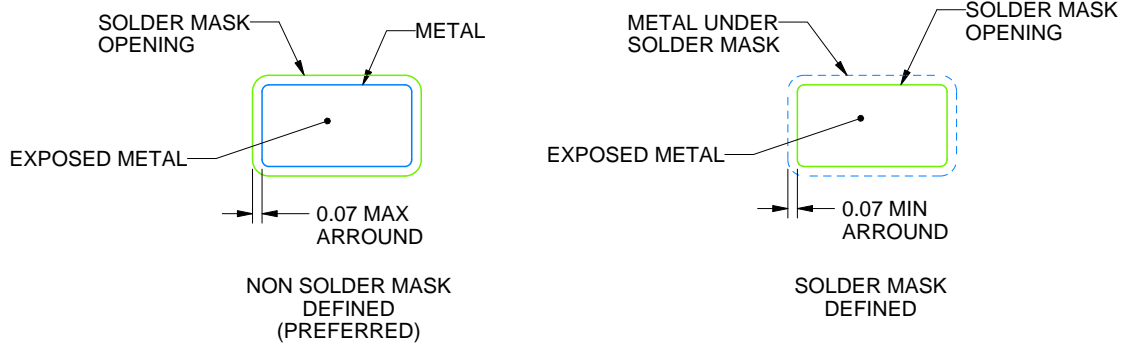
DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X



SOLDER MASK DETAILS

4214840/B 03/2018

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

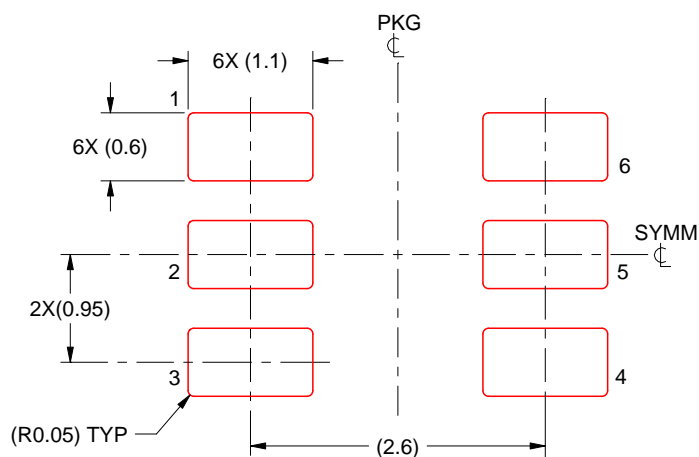
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:15X

4214840/B 03/2018

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2019, Texas Instruments Incorporated